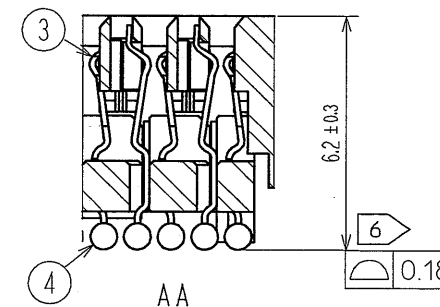
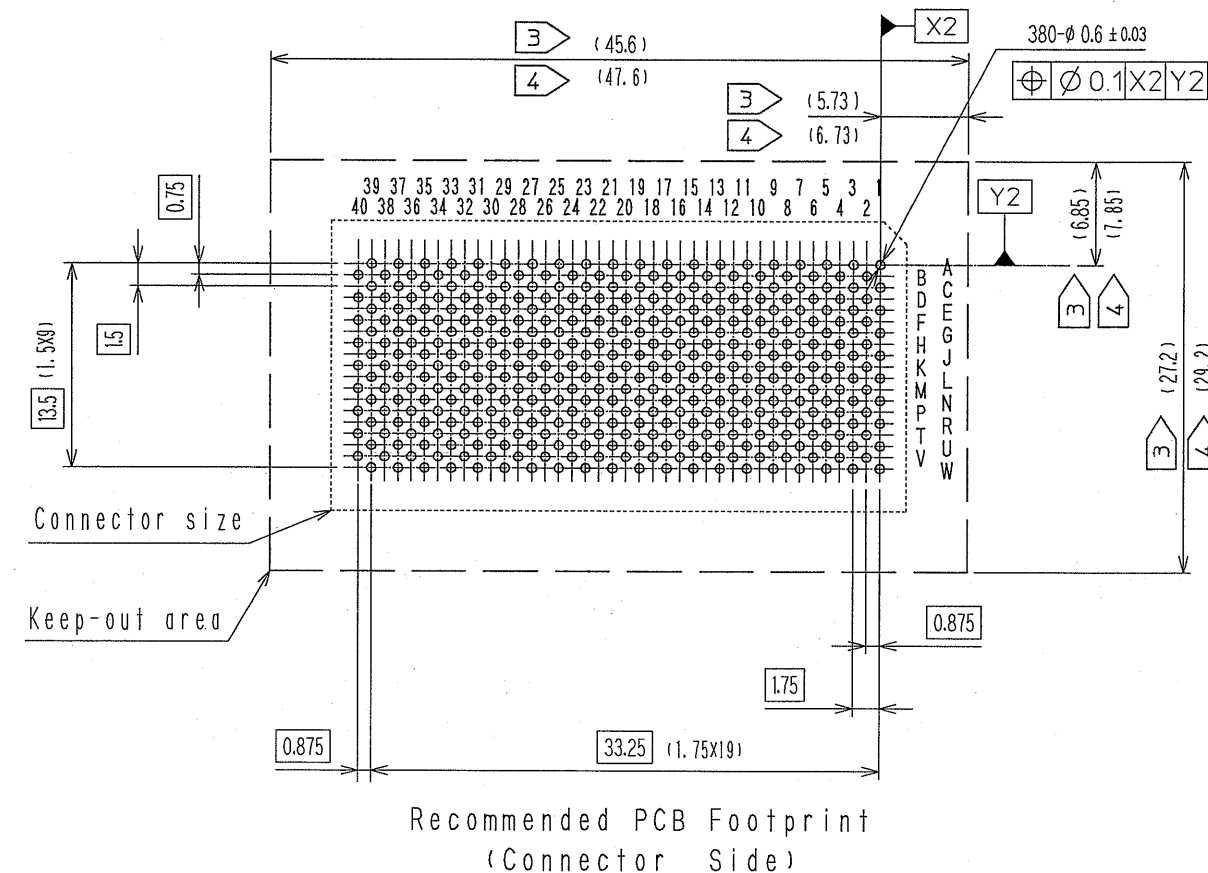
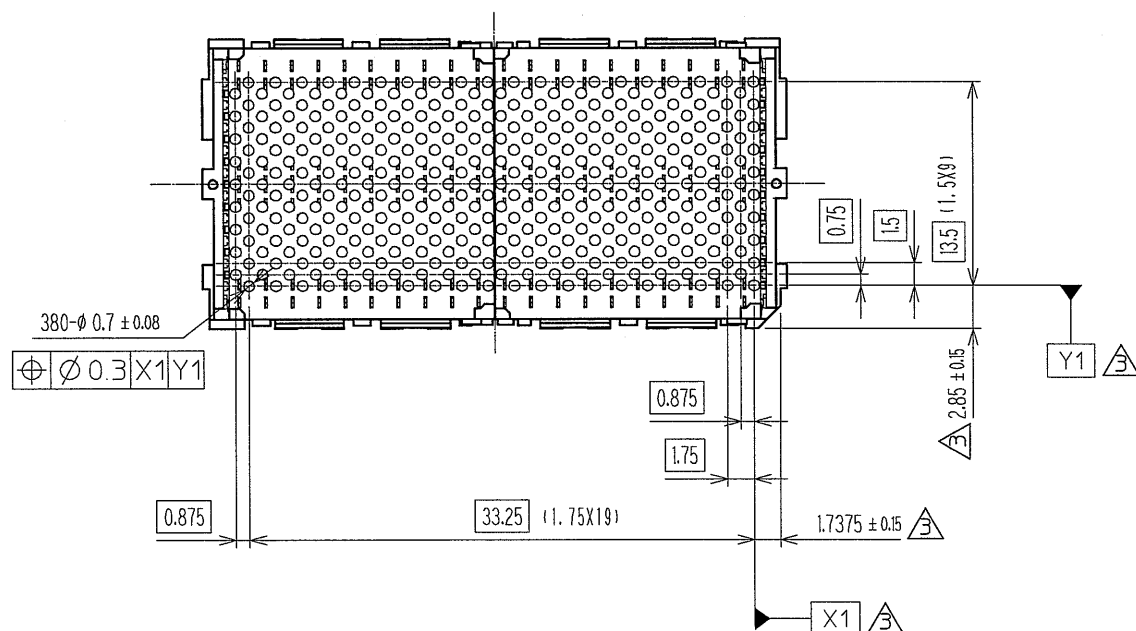
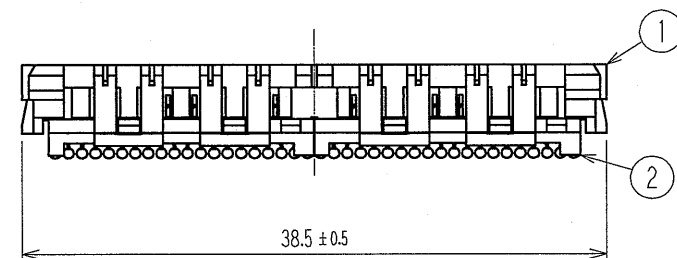
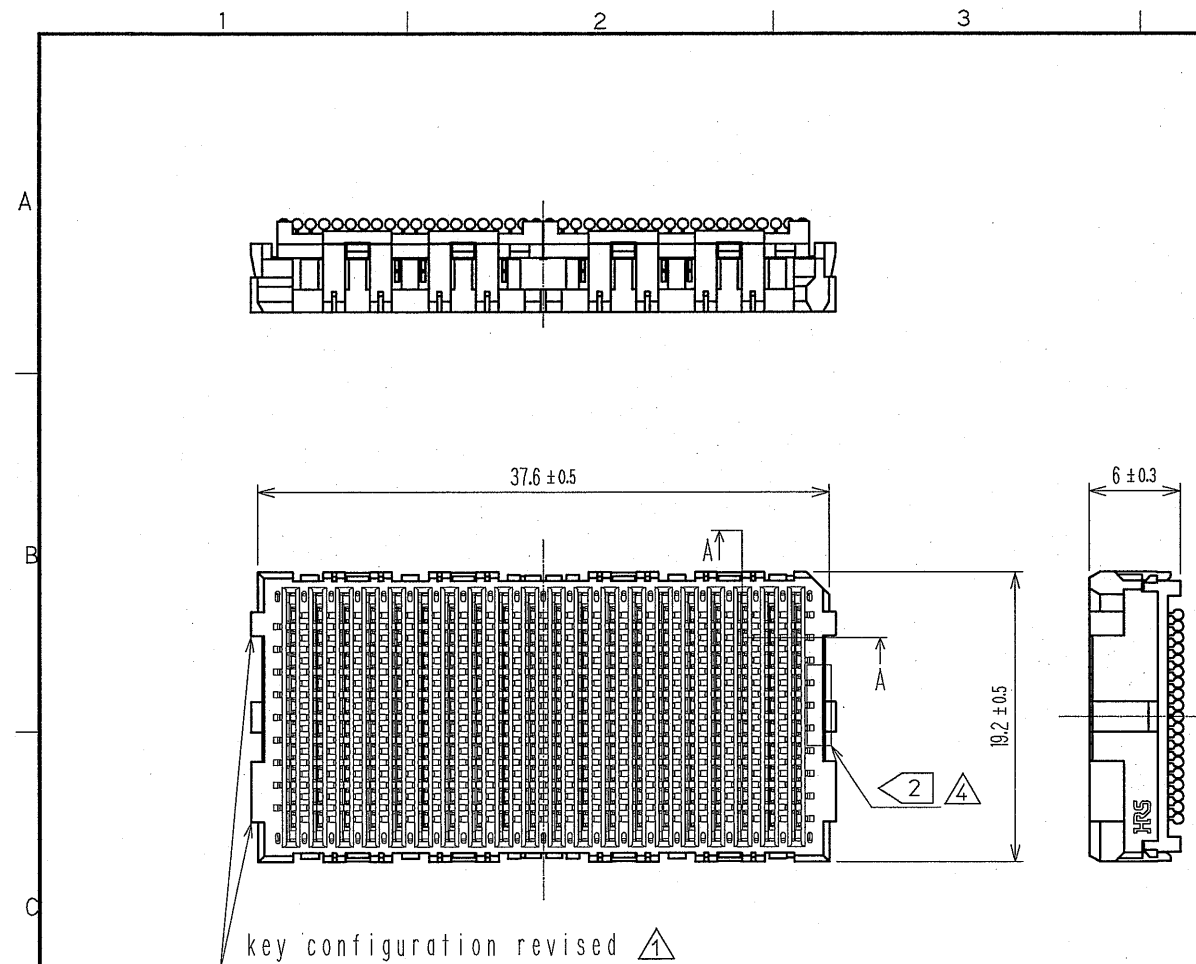
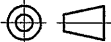




NOTE

- 1 IT3-200P-**H(**) to be mounted and locked to IT3M receptacle.
- 2 Lot no. is marked on top of the connector.
- 3 Minimum clearance for all devices.
- 4 Minimum clearance for sensitive devices.
- 5 More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".
- 6 Maximum coplanarity of the ball field is 0.18 mm.
- 7 Standard package of 72pcs are packaged in a carton box.
- 8 This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.
- 9 This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

3	Copper alloy	Contact area : Nickel(1.5μm) + Gold(0.76μm)			
		Other area : Nickel(1.5μm)		6	NORMEX
2	LCP	BLACK , UL94V-0		5	HIPS
1	LCP	BLACK , UL94V-0		4	TIN
NO.	MATERIAL	FINISH, REMARKS		NO.	MATERIAL

UNITS mm			SCALE 2 : 1	REV 	COUNT 3	DESCRIPTION OF REVISIONS DIS-F-004000	DESIGNED T. Saito	CHECKED M. Ezaki	DATE 15. July. 09
 HIROSE ELECTRIC CO., LTD.			APPROVED : T. Matsuo		07/26/2007	DRAWING NO. EDC3-156952-03			
			CHECKED : T. Matsuo		07/26/2007	PART NO. IT3M-200S-BGA(37)			
			DESIGNED : T. Takada		07/26/2007	CODE NO. CL636-0004-0-37			
			DRAWN : T. Takada		07/26/2007	 1/5			

